

FLC-BTM701



概述：

FLC-BTM701是一款高性价比的小型低功耗蓝牙无线模组，设备制造商可通过此模块在其产品上增加无线通讯功能。此模块支持多重类型

Description:

FLC-BTM701 is a small form factor, low power and highly economic Bluetooth radio module that allows OEM to add wireless capability to their products.

设计不同的应用程序以支持各种协议，如SPP,DUN,HDP等。该模块支持蓝牙增强型数据传输与蓝牙5.0，10m内传输速率可达到3Mbps。此模块是无线产品设计者们的理想选择。

技术规格：

- ◆ 蓝牙版本与技术：双模 蓝牙5.0
- ◆ 嵌入的蓝牙协议：SPP, DUN, HDP等，具体由固件决定
- ◆ 接口：UART, PIO, AIO, USB2.0, SPI, PCM
- ◆ 发射功率：7dBm (最大9dBm)
- ◆ 天线：板上天线设计
- ◆ 内置80MIPS处理器与SPI内存
- ◆ 温度：-40°C到+85°C
- ◆ 尺寸：13.40mm x 25.80mm x 2.40mm

应用：

- ◆ 条形码和射频识别扫描
- ◆ 导线替代
- ◆ 测量与监控系统
- ◆ 工业控制与传感
- ◆ 医疗设备
- ◆ 工业电脑

Through various interfaces, designers can easily customize their applications to support different Bluetooth profiles, such as SPP, DUN, HDP, and etc. The module supports Bluetooth Enhanced Data Rate (EDR), BT5.0 and delivers up to 3 Mbps data rate for distances to 10M.

The module is an appropriate product for designers who want to add wireless capability to their products.

Technical Specification:

- ◆ BT version and technology: Fully qualified single-chip dual mode Bluetooth v5.0
- ◆ Embedded Profiles: SPP, DUN, HDP, etc. detailed profiles depends on the firmware
- ◆ Interfaces: UART, PIO, AIO, USB2.0, SPI, PCM
- ◆ RF TX Power: 7dBm (Max: 9dBm)
- ◆ Antenna: On-board antenna design
- ◆ Built-in 80MIPS processor and SPI flash
- ◆ Temperature: -40°C to +85°C
- ◆ Size: 13.40mm x 25.80mm x 2.40mm

Application:

- ◆ Bar code and RFID scanning
- ◆ Cable replacements
- ◆ Measurement and monitoring systems
- ◆ Industrial sensors and controls
 - ◆ Medical devices
 - ◆ Industrial PCs and laptops